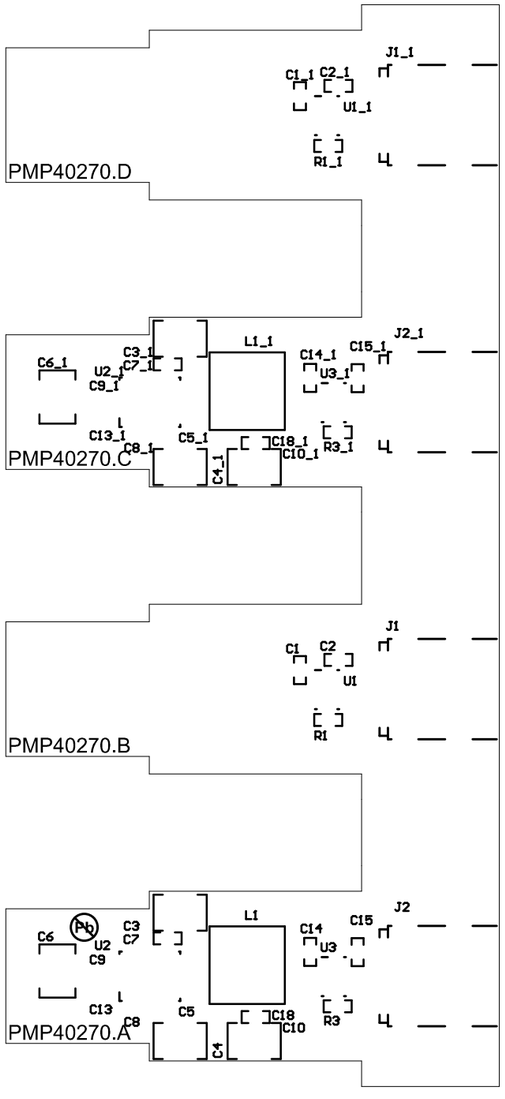
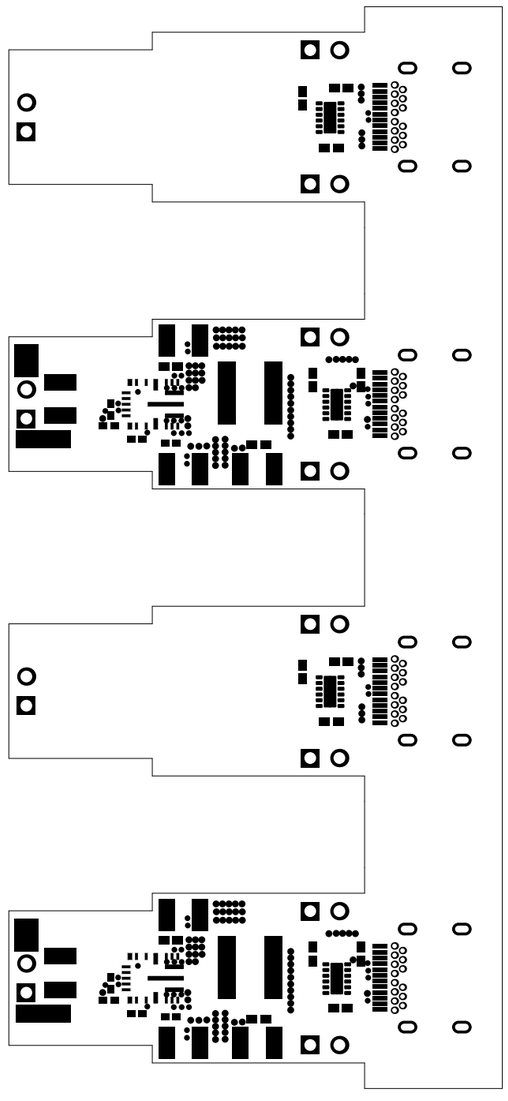
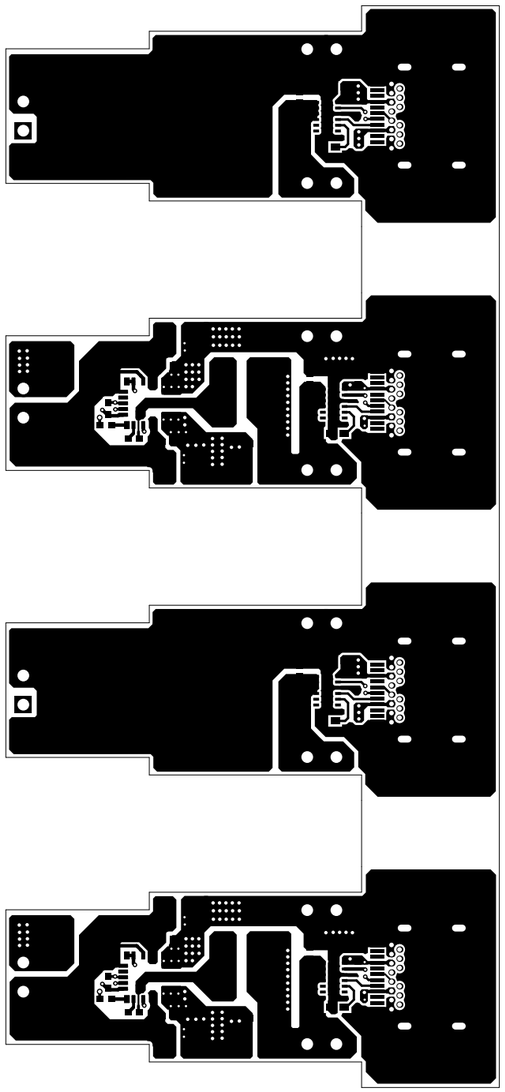
ZZ2
ZZ3
ZZ4



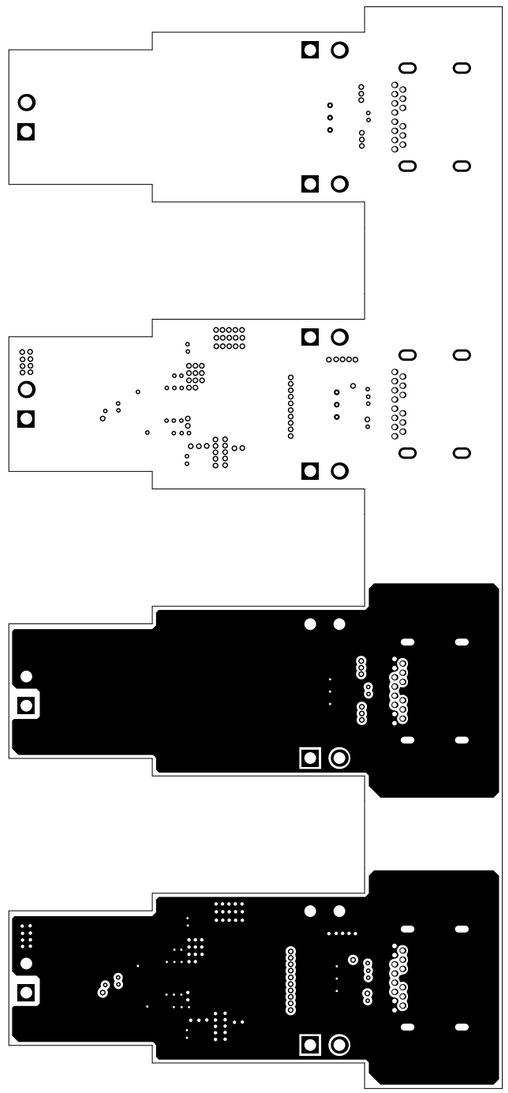
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40270	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP40270		
PLOT NAME = Top Overlay	GENERATED : 11/20/2017 11:00:01 AM		TEXAS INSTRUMENTS



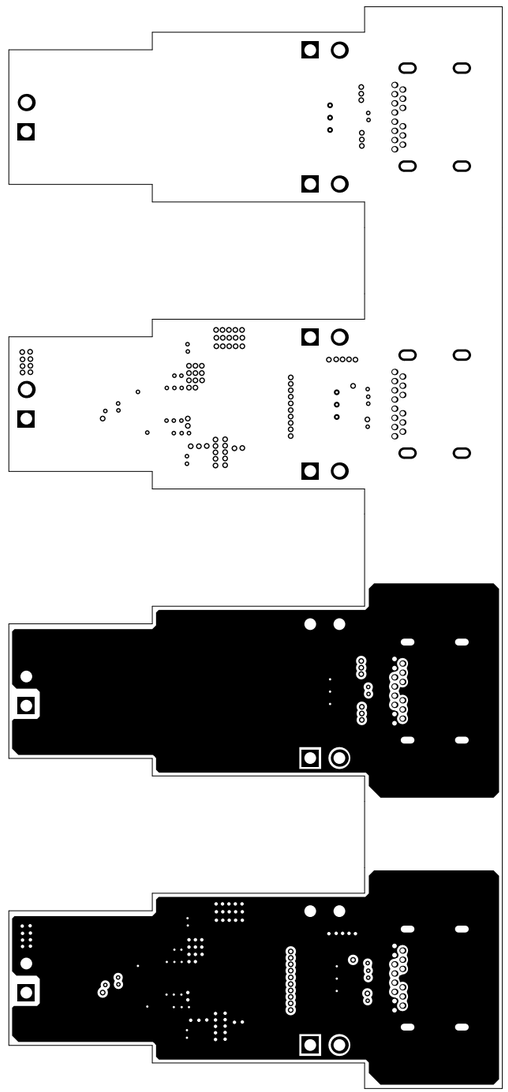
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40270	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP40270		
PLOT NAME = Top Solder Mask	GENERATED : 11/20/2017 11:00:02 AM		TEXAS INSTRUMENTS



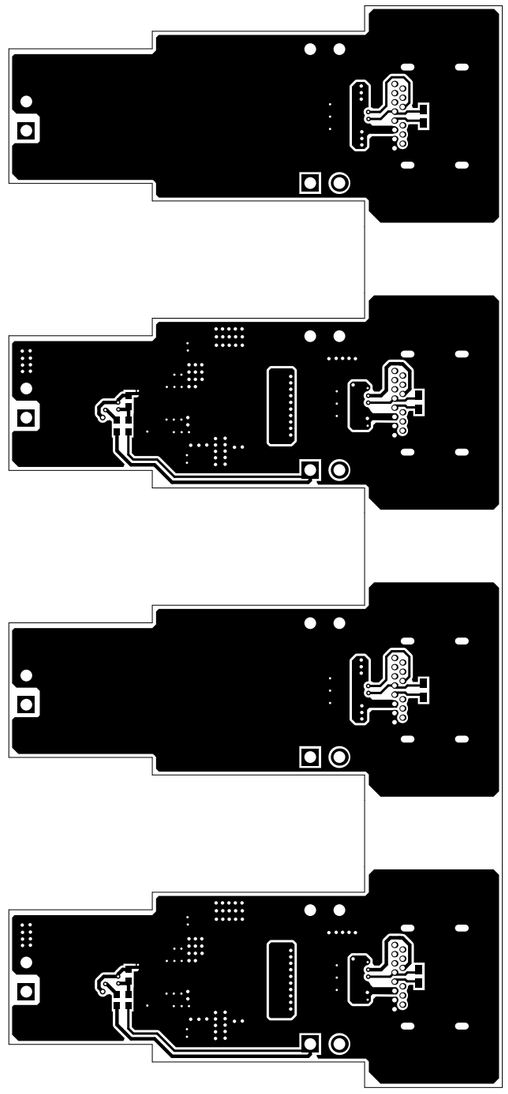
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40270	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP40270		
PLOT NAME = Top Layer	GENERATED : 11/20/2017 11:00:03 AM		TEXAS INSTRUMENTS



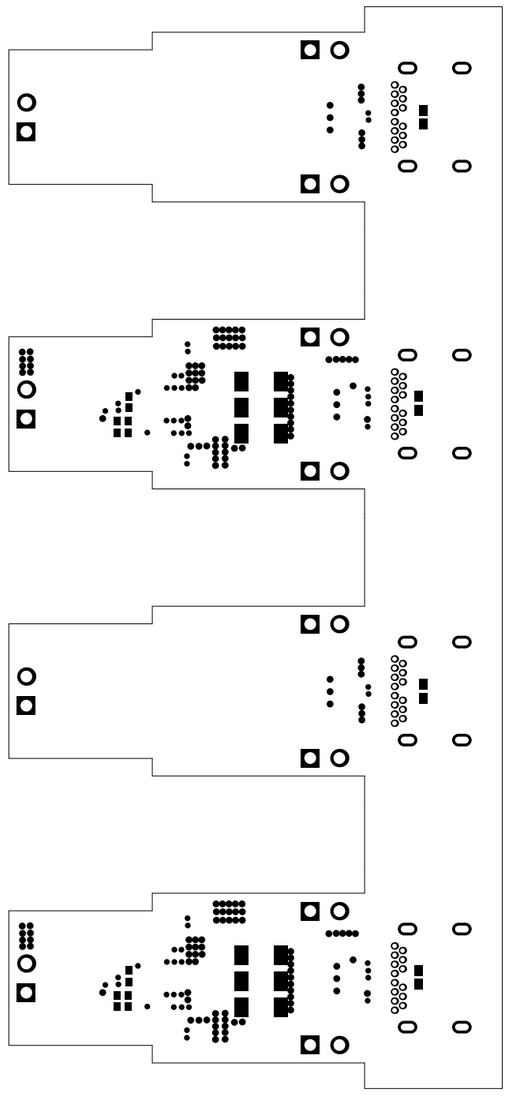
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40270	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40270		
PLOT NAME = Signal Layer 1	GENERATED : 11/20/2017 11:00:04 AM		TEXAS INSTRUMENTS



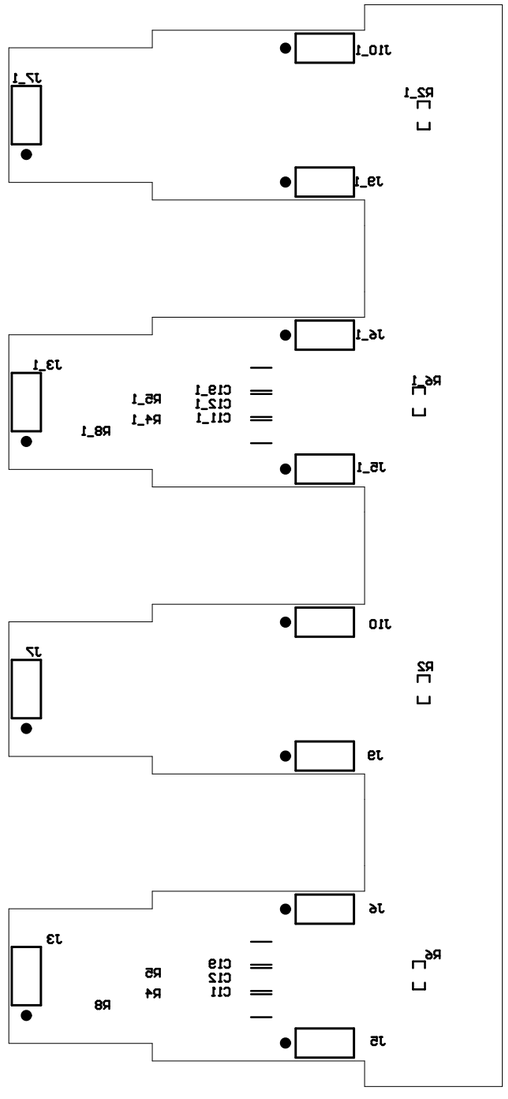
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40270	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40270		
PLOT NAME = Signal Layer 2	GENERATED : 11/20/2017 11:00:05 AM		TEXAS INSTRUMENTS



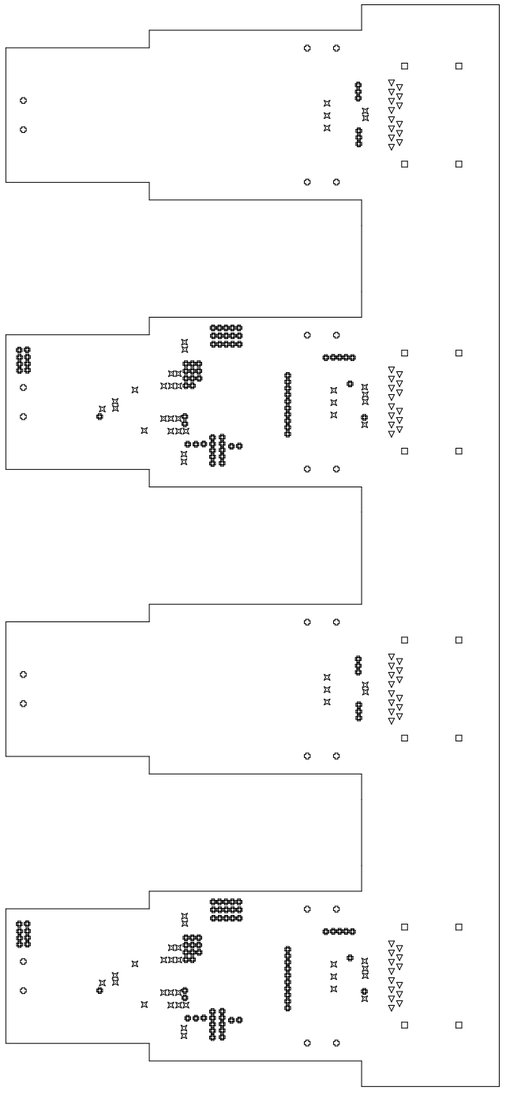
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40270	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP40270		
PLOT NAME = Bottom Layer	GENERATED : 11/20/2017 11:00:06 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40270	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP40270		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/20/2017 11:00:07 AM		TEXAS INSTRUMENTS



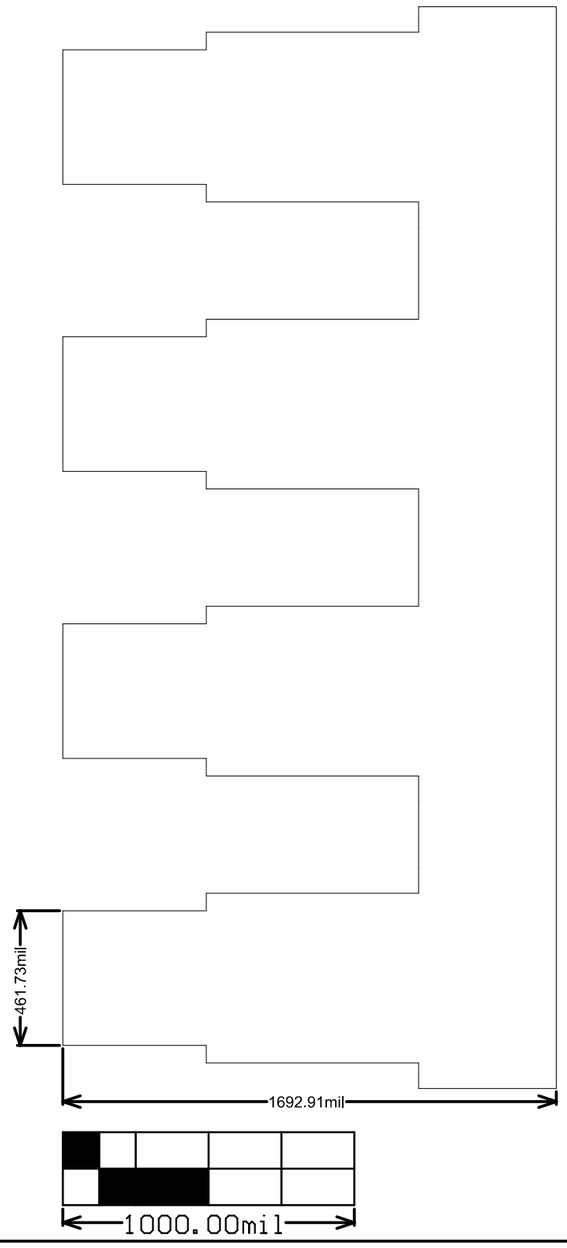
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40270	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP40270		
PLOT NAME = Bottom Overlay	GENERATED : 11/20/2017 11:00:08 AM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
	64	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
	150	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
	56	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	
	24	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
	16	23.62mil (0.600mm)	PTH	Slot	Top Layer - Bottom Layer	
	310 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40270	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP40270		
PLOT NAME = Drill Drawing	GENERATED : 11/20/2017 11:00:09 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40270	REV: A	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP40270		
PLOT NAME = Board Dimensions	GENERATED : 11/20/2017 11:00:11 AM		TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265